

■ HPS-S01-008

Designed for applications up to 12 GHz in the common high frequency substrates and it is suitable for military and microwave frequencies.



SMA End-Launch Jack

Specification

Electrical

Frequency	DC to 12.0 GHz
Impedance	50 Ω
VSWR (Only Connector)	1.2:1(@10 GHz), 1.7:1(@12 GHz)
Insulation Resistance	5000 MΩ
Dielectric Withstand Voltage	1000 Vrms max.
Contact resistance	
- Outer Conductor	2mΩ max.
- Inner Conductor	3mΩ max.

Mechanical

Mating Cycle (Durability)	500
Recommended Mating Torque	57 Ncm
Center Contact Retention (Axial)	26.7 N

Environmental

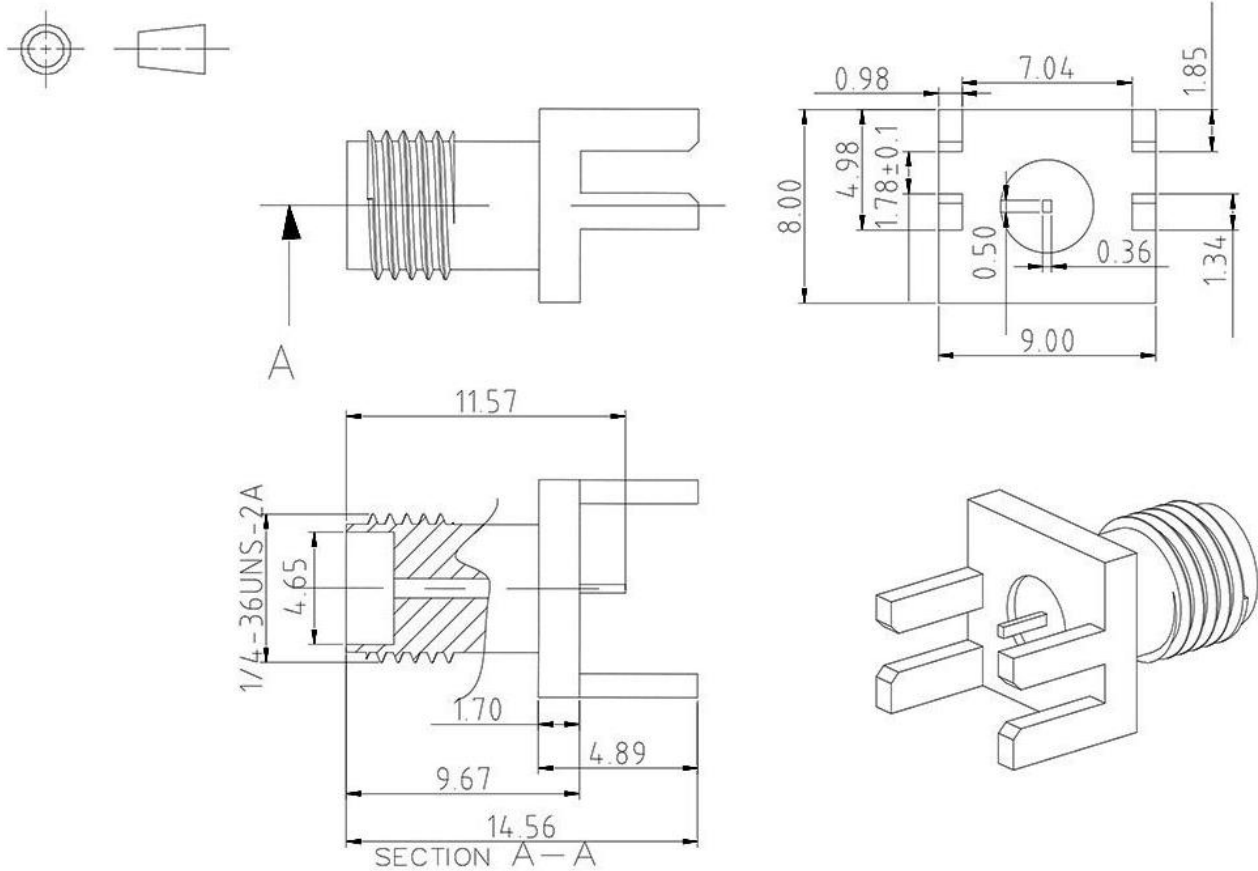
Temperature	-40 °C up to +125 °C
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Compliance

	RoHS
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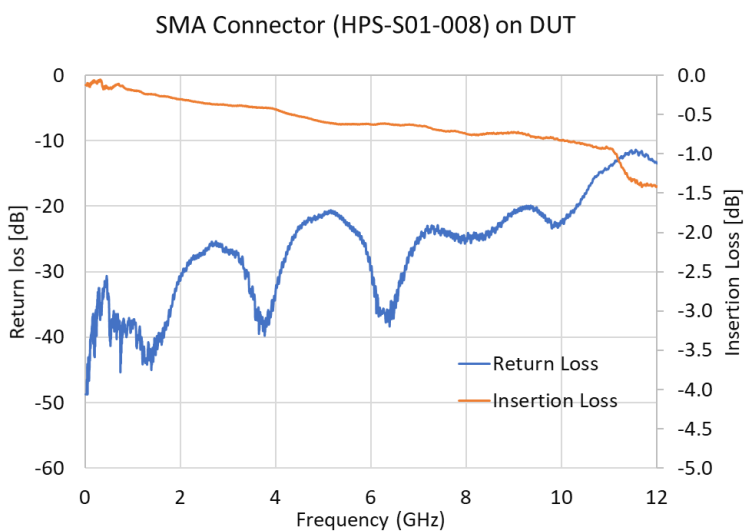
Materials

Body	Brass	Gold Plated
Center Contact	Beryllium Copper (BeCu)	Gold Plated
Insulator	PTFE	White



Unit: mm

Performance



DUT

Connector

- HPS-S01-008: 2 ps.
- PCB 4 layer
 - Top dielectric FR-4 High Speed (TUC872 SLK) 0.254 mm
 - PCB Thickness 1.5 mm
 - CPWG 50 Ω Line: Width: 0.45 mm, Gap: 0.3 mm, Length: 29 mm

